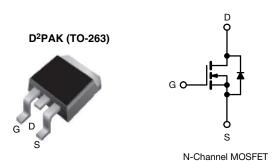
COMPLIANT

HALOGEN

FREE

Vishay Siliconix

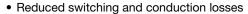
E Series Power MOSFET



PRODUCT SUMMARY					
V_{DS} (V) at T_J max.	850				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	1.1			
Q _g max. (nC)	32				
Q _{gs} (nC)	4				
Q _{gd} (nC)	6				
Configuration	Single				

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)



- Ultra low gate charge (Qa)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION			
Package	D ² PAK (TO-263)		
Lead (Pb)-free and halogen-free	SiHB4N80E-GE3		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	800	V	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V at 10 V	T _C = 25 °C T _C = 100 °C		4.3	А	
	V _{GS} at 10 V	T _C = 100 °C	I _D	2.7		
Pulsed drain current ^a			I _{DM}	11		
Linear derating factor			0.56	W/°C		
Single pulse avalanche energy b			E _{AS}	56	mJ	
Maximum power dissipation			P _D	69	W	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope	$T_{J} = T_{J}$	T _J = 125 °C		70	\//no	
Reverse diode dV/dt ^d		dV/dt	0.3	V/ns		
Soldering recommendations (peak temperature)	c For	For 10 s		260	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 2.0 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	-	1.8	G/ VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		800	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	1.1	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu A$		-	4.0	V
Outros and test and	I _{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage		,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zana mata walta sa aluaisa awanant		V _{DS} =	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 640 V	V _{DS} = 640 V, V _{GS} = 0 V, T _J = 125 °C		-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 2 A	-	1.1	1.27	Ω
Forward transconductance	9 _{fs}	V_{DS}	V _{DS} = 30 V, I _D = 2 A		1.5	-	S
Dynamic		•				•	
Input capacitance	C _{iss}	$V_{GS} = 0 V$,		-	622	-	pF
Output capacitance	C _{oss}	,	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz		34	-	
Reverse transfer capacitance	C _{rss}				5	-	
Effective output capacitance, energy related ^a	C _{o(er)}			-	21	-	
Effective output capacitance, time related ^b	$C_{o(tr)}$	$V_{DS} = 0$	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$		91	-	
Total gate charge	Qg			-	16	32	1
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 2 \text{ A}, V_{DS} = 480 \text{ V}$		4	-	nC
Gate-drain charge	Q _{gd}				6	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 480 V, I _D = 2 A,		-	12	24	- ns
Rise time	t _r			-	7	14	
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		26	52	
Fall time	t _f			-	20	40	
Gate input resistance	R_g	f = 1 MHz, open drain		0.6	1.2	2.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	4.4	
Pulsed diode forward current	I _{SM}			-	-	11	- A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 2 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	-	-3, -3, -3		248	496	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 2 \text{A},$ $dI/dt = 100 \text{A/}\mu\text{s}, V_R = 25 \text{V}$		-	1.4	2.8	μC
Reverse recovery current	I _{RRM}			_	9.2	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

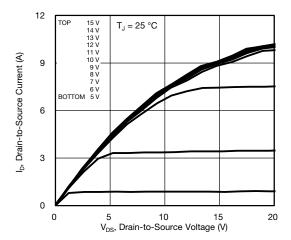


Fig. 1 - Typical Output Characteristics

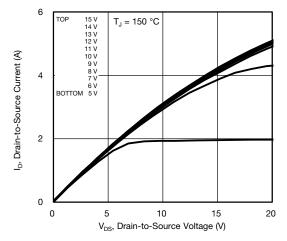


Fig. 2 - Typical Output Characteristics

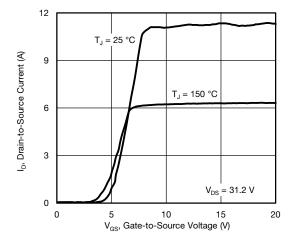


Fig. 3 - Typical Transfer Characteristics

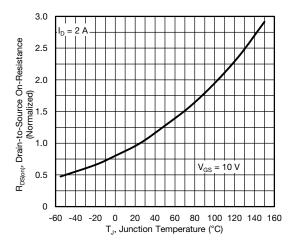


Fig. 4 - Normalized On-Resistance vs. Temperature

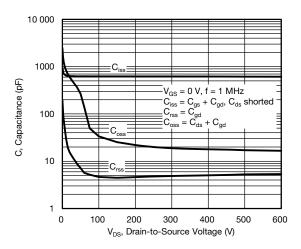


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

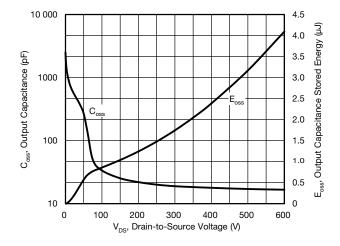


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



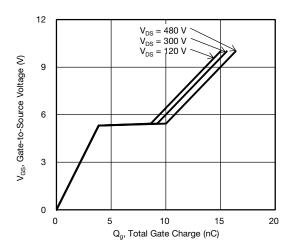


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

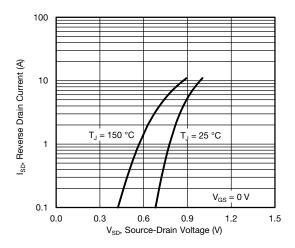


Fig. 8 - Typical Source-Drain Diode Forward Voltage

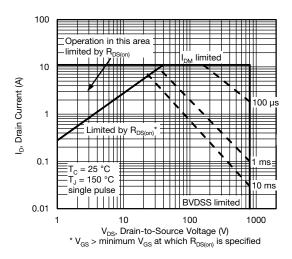


Fig. 9 - Maximum Safe Operating Area

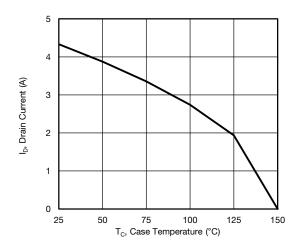


Fig. 10 - Maximum Drain Current vs. Case Temperature

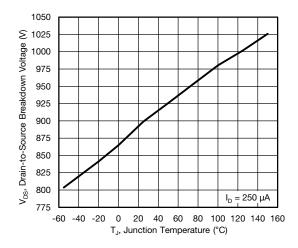


Fig. 11 - Temperature vs. Drain-to-Source Voltage



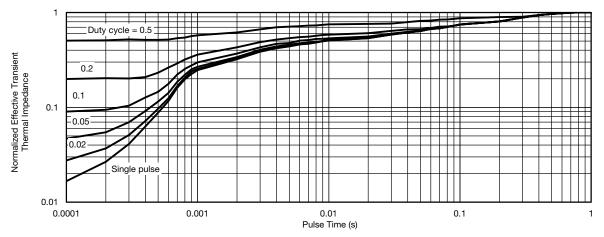


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

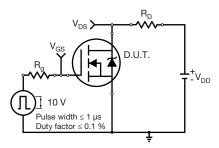


Fig. 13 - Switching Time Test Circuit

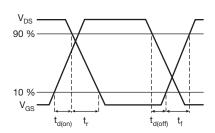


Fig. 14 - Switching Time Waveforms

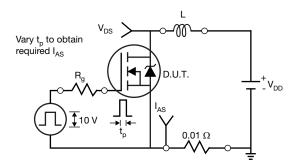


Fig. 15 - Unclamped Inductive Test Circuit

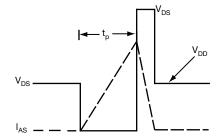


Fig. 16 - Unclamped Inductive Waveforms

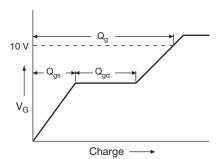


Fig. 17 - Basic Gate Charge Waveform

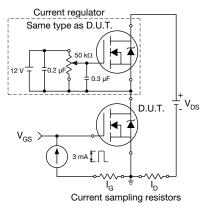
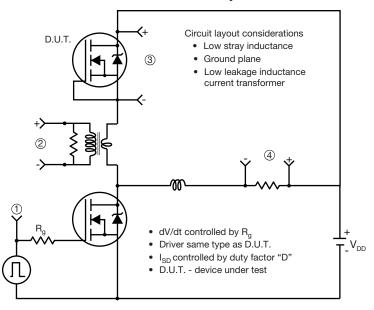


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



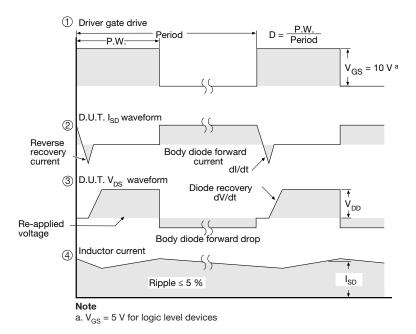


Fig. 19 - For N-Channel

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